

Product Change Notice (PCN)

Date: 07/19/2023

PCN Number: **PCN-045-0002R-01**

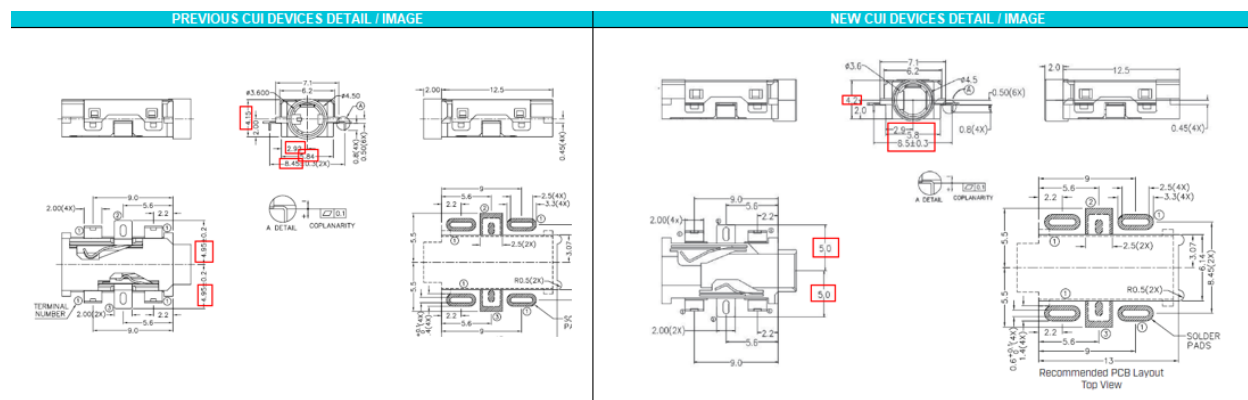
To Our Customers:

We appreciate your use of our products. Our commitment in maintaining and improving processes is demonstrated by plans to enhance our product quality, reliability, and manufacturability. The purpose of this notice is to inform you of a product change.

Product(s) Affected: *SJ-3502-SMT-TR*

Reason(s) for Change: *Manufacturing Process Improvements*

Description of Change: *Minor structural change, solder profile and packaging difference. See image below.*



F-723-001

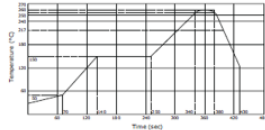
Revision: A

PREVIOUS CUI DEVICE'S DETAIL / IMAGE **NEW CUI DEVICE'S DETAIL / IMAGE**

SOLDERABILITY

parameter	conditions/description	min	typ	max	units
reel storage	at relative humidity <80%			40	°C
reflow soldering ¹	see reflow profile	255	260	265	°C
drying conditions ²	parts in reel: bake at 40°C ±5°C for 72 hours parts removed from reel: bake at 40°C ±5°C for 10 hours				

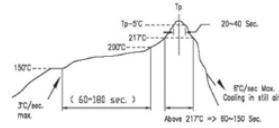
Note: 1. It is recommended to reflow solder within 72 hours from opening vacuum packaging at a temperature >35°C & relative humidity <60%.
2. When exceeding 90% by >72 hours.



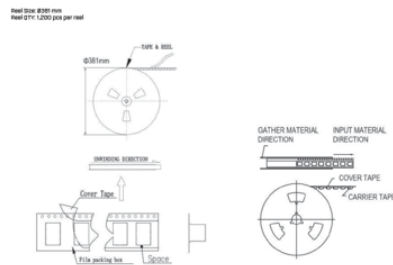
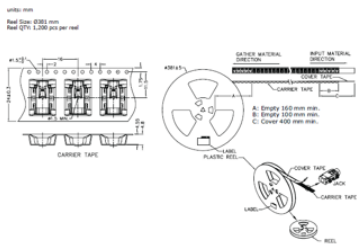
SOLDERABILITY

parameter	conditions/description	min	typ	max	units
reel storage ¹	10-30°C, <70% humidity				°C
reflow soldering ²	see reflow profile	255	260		°C
drying conditions ²	parts in reel: bake at 110°C for 4 hours parts removed from reel: bake at 110°C for 4 hours				

Note: 1. CUI Devices recommends to solder within 72 hours from opening vacuum packaging at a temperature >30°C & relative humidity <60%.
2. When exceeding 90% by >72 hours.



* Time 25°C to Peak Temp. --- 8 Minutes Max.
* Time within 5°C of Actual Peak Temp. --- 20-40 Seconds



Affected Date Code: **07/10/2023**

Product Availability: *Pertaining to market availability*

PCN Approval:

Operations/Quality



Product Management

